

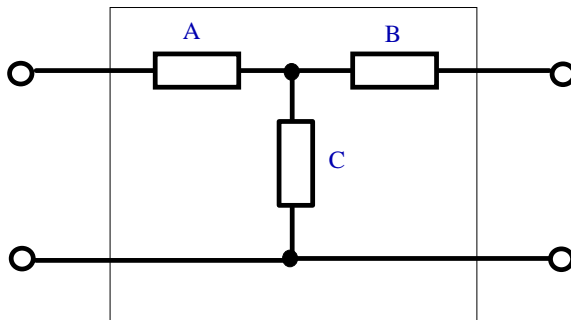
**3.3.3.3:
TESTING S-PARAMETERS FOR TYPICAL PASSIVE CIRCUITS**

This chapter is divided into a first section, interpreting measured S-parameters against either a TEE *or* a PI structure, and a second section, where the data is tested against a *cascade* of a PI and a TEE structure. The lumped components are inductors, resistors and capacitors.

RLC_TEE OR RLC_PI CIRCUITS

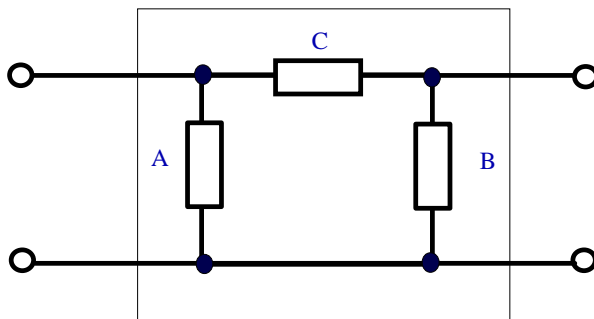
IC_CAP file: pass_RLC_TEE_or_PI.mdl

This chapter is intended to present some matrix manipulations for the interpretation of S-parameters of typical passive LRC networks. This is done by transforming the S-parameters to Y or Z-parameters. For these types of matrices exist simple interpretation capabilities, provided their underlying circuits have a structure like in figures 1 and 2.



$$Z_{TEE} = \begin{pmatrix} A+C & C \\ C & B+C \end{pmatrix}$$

Fig.1: a TEE circuit interpreted as a Z matrix.



$$Y_{PI} = \begin{pmatrix} A+C & -C \\ -C & B+C \end{pmatrix}$$

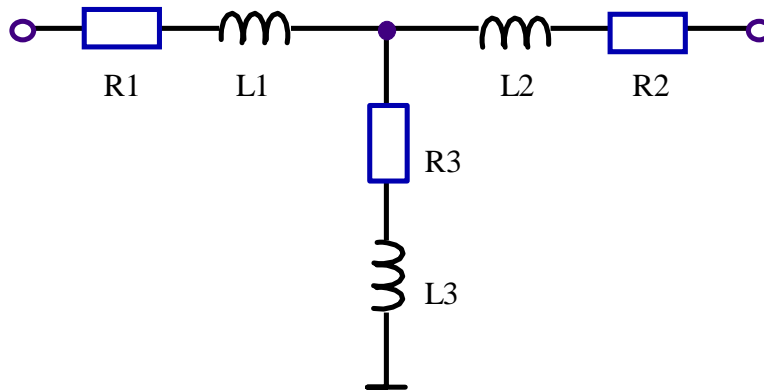
watch the signs! .

Fig.2: a PI circuit interpreted as a Y matrix.

3.3.3.3: Testing S-Parameters for typical passive circuits -2-

The following examples cover modeling algorithms for typical passive LRC networks.

Circuit 1:



This circuit has a TEE structure and therefore we have to interpret it following fig.1. That's why we transform the S parameters to Z and calculate the auxiliary variable

$$Z_{xy} = (Z_{12} + Z_{21}) / 2$$

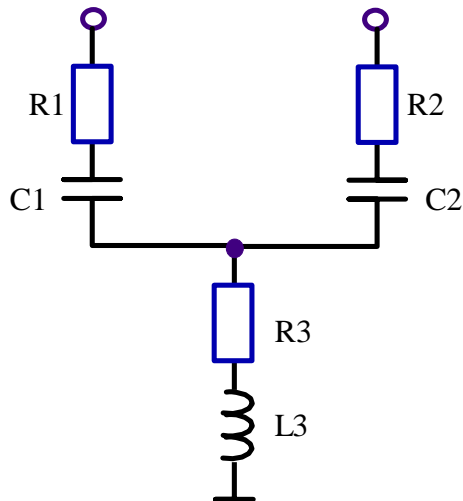
Then, we obtain for the circuit elements from fig.1:

$$\begin{aligned} A &= Z_{11} - Z_{xy} \\ B &= Z_{22} - Z_{xy} \\ C &= Z_{xy} \end{aligned}$$

Out of that, we can now calculate the parameter values of the elements of our circuit:

$$\begin{aligned} R1 &= \text{REAL}(A) & L1 &= \frac{\text{IMAG}(A)}{2 * \text{PI} * \text{freq}} \\ R2 &= \text{REAL}(B) & L2 &= \frac{\text{IMAG}(B)}{2 * \text{PI} * \text{freq}} \\ R3 &= \text{REAL}(C) & L3 &= \frac{\text{IMAG}(C)}{2 * \text{PI} * \text{freq}} \end{aligned}$$

Circuit 2:



This circuit which is a typical one for an OPEN dummy on a silicon wafer has a TEE structure. So, again, we interpret it following fig.1. To do so, we have to transform the S parameters to Z, calculate

$$Z_{xy} = (Z_{12} + Z_{21}) / 2$$

and obtain for the circuit elements of fig.1:

$$A = Z_{11} - Z_{xy}$$

$$B = Z_{22} - Z_{xy}$$

$$C = Z_{xy}$$

Back to our actual circuit, we get for its parameter values:

$$R1 = \text{REAL}(A)$$

$$C1 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}(A)}$$

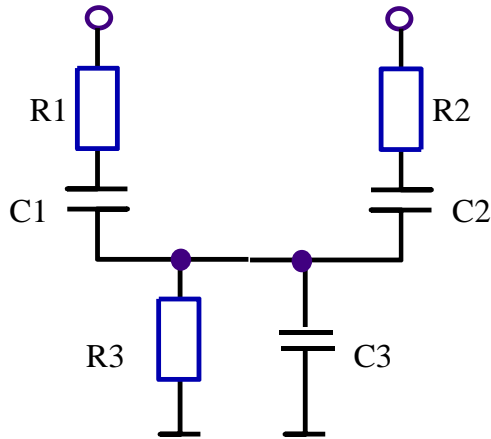
$$R2 = \text{REAL}(B)$$

$$C2 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}(B)}$$

$$R3 = \text{REAL}(C)$$

$$L3 = \frac{\text{IMAG}(C)}{2 * \text{PI} * \text{freq}}$$

Circuit 3:



This circuit is a variation of the circuit 2. Again, we interpret it following fig.1, i.e. we have to transform the S parameters to Z, calculate

$$Z_{xy} = (Z_{12} + Z_{21}) / 2$$

and obtain for the circuit elements of fig.1:

$$A = Z_{11} - Z_{xy}$$

$$B = Z_{22} - Z_{xy}$$

$$C = Z_{xy}$$

Back to our actual circuit, we get for its parameter values:

$$R1 = \text{REAL}(A)$$

$$C1 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}(A)}$$

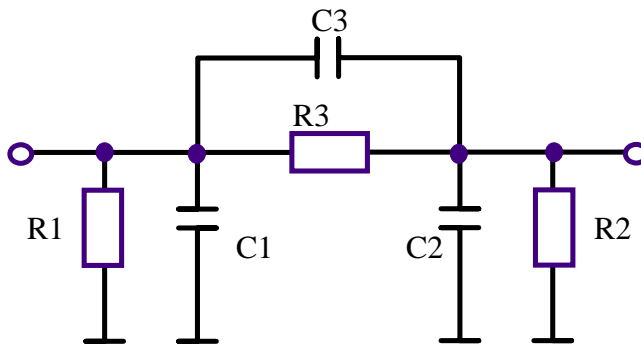
$$R2 = \text{REAL}(B)$$

$$C2 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}(B)}$$

$$R3 = \frac{1}{\text{REAL}\left(\frac{1}{C}\right)}$$

$$C3 = \frac{\text{IMAG}\left(\frac{1}{C}\right)}{2 * \text{PI} * \text{freq}}$$

Circuit 4:



In this case, the circuit behaves like a PI structure and so we have to interpret it after fig.2. Transforming the S parameters to Y and calculating

$$Y_{xy} = (Y_{12} + Y_{21}) / 2$$

we get for the circuit elements of fig.2:

$$A = Y_{11} + Y_{xy}$$

$$B = Y_{22} + Y_{xy}$$

$$C = -Y_{xy}$$

Finally, the parameter values of our actual circuits are:

$$R1 = \frac{1}{\text{REAL}(A)}$$

$$C1 = \frac{\text{IMAG}(A)}{2 * \text{PI} * \text{freq}}$$

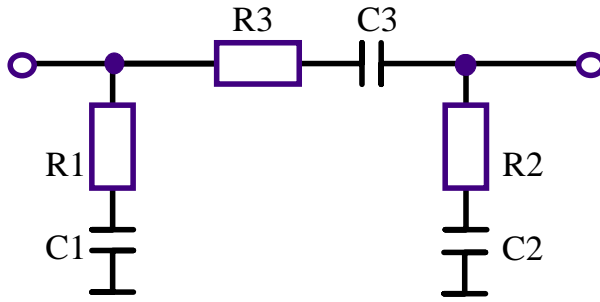
$$R2 = \frac{1}{\text{REAL}(B)}$$

$$C2 = \frac{\text{IMAG}(B)}{2 * \text{PI} * \text{freq}}$$

$$R3 = \frac{1}{\text{REAL}(C)}$$

$$C3 = \frac{\text{IMAG}(C)}{2 * \text{PI} * \text{freq}}$$

Circuit 5:



Transforming the S parameters to Y and interpreting them as a PI structure (fig.2), we get using

$$Y_{xy} = (Y_{12} + Y_{21}) / 2$$

the circuit elements

$$A = Y_{11} + Y_{xy}$$

$$B = Y_{22} + Y_{xy}$$

$$C = -Y_{xy}$$

Out of them, we can calculate the parameter values of the actual circuit to

$$R1 = \text{REAL}\left(\frac{1}{A}\right)$$

$$C1 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}\left(\frac{1}{A}\right)}$$

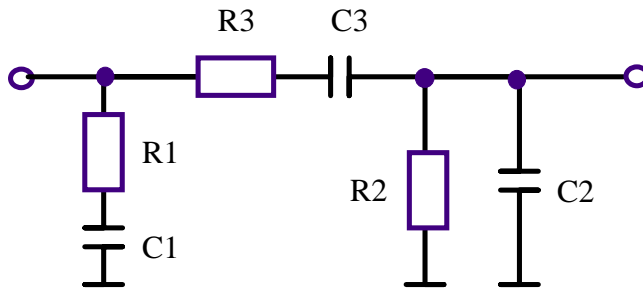
$$R2 = \text{REAL}\left(\frac{1}{B}\right)$$

$$C2 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}\left(\frac{1}{B}\right)}$$

$$R3 = \text{REAL}\left(\frac{1}{C}\right)$$

$$C3 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}\left(\frac{1}{C}\right)}$$

Circuit 6:



This example also looks like a PI structure and therefore we transform again the S parameters to Y and obtain for the circuit elements of fig.2 using:

$$Y_{xy} = (Y_{12} + Y_{21}) / 2$$

$$A = Y_{11} + Y_{xy}$$

$$B = Y_{22} + Y_{xy}$$

$$C = -Y_{xy}$$

This leads to the parameters of our actual example.

We get for R1 and C1:

$$R1 = \text{REAL}\left(\frac{1}{A}\right)$$

$$C1 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}\left(\frac{1}{A}\right)}$$

and for R2 and C2:

$$R2 = \frac{1}{\text{REAL}(B)}$$

$$C2 = \frac{\text{IMAG}(B)}{2 * \text{PI} * \text{freq}}$$

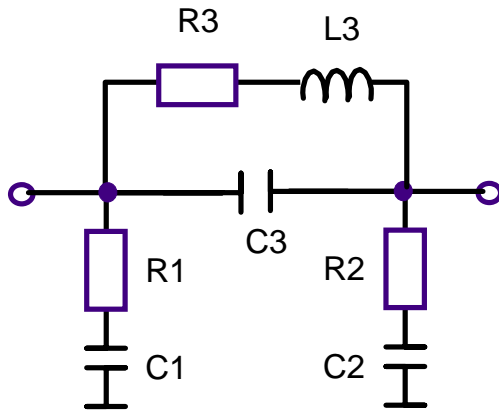
as well as for R3 and C3:

$$R3 = \text{REAL}\left(\frac{1}{C}\right)$$

$$C3 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}\left(\frac{1}{C}\right)}$$

The implementation of these formulas into IC-CAP is very simple using PEL and can be looked at in the model file.

Circuit 7:



This example is another PI structure and therefore we transform again the S parameters to Y and obtain for the circuit elements of fig.2 using:

$$Y_{xy} = (Y_{12} + Y_{21}) / 2$$

$$A = Y_{11} + Y_{xy}$$

$$B = Y_{22} + Y_{xy}$$

$$C = -Y_{xy}$$

We get for R1 and C1:

$$R1 = \text{REAL}\left(\frac{1}{A}\right)$$

$$C1 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}\left(\frac{1}{A}\right)}$$

and for R2 and C2:

$$R2 = \text{REAL}\left(\frac{1}{B}\right)$$

$$C2 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}\left(\frac{1}{B}\right)}$$

as well as for R3, C3 and L3:

$$R3 = \text{REAL}\left(\frac{1}{C}\right)$$

extract from data before resonance,
at low frequencies

$$L3 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}(C)}$$

extract from data before resonance,
at low frequencies

$$C3 = \frac{-1}{2 * \text{PI} * \text{freq} * \text{IMAG}\left(\frac{1}{C}\right)}$$

extract from data after resonance,
at high frequencies

APPLICATION: modeling of spiral inductors

CASCADED RLC_TEE AND RLC_PI CIRCUITS

IC_CAP file: pass_RLC_TEE_and_PI.mdl

This chapter is currently under development.